



# Kunshan Jiahua Electronics Co., Ltd.

文件名称 System Name:	产品品名 Description:	文件编号 Document No.:		
Product specification	Micro SD 0.3H 豆腐块	PS-0100		
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## 1. 概述 **Scope:**

### 1.1 说明 **Content**

此份产品规格书是针对由昆山嘉华电子有限公司设计和制造的 **Micro SD 0.3H 豆腐块 CONN.** 产品所定义的产品性能和测试方法。

This product specification defines the product performance and the test methods to ensure the performance of the **Micro SD 0.3H CONN.**, which is designed and manufactured by Kunshan Jiahua Electronics Co., Ltd.

### 1.2 限制 **Qualification**

所有的测试和检验必须依照本文件中所要求的规格、方法进行。一旦产品的重要制程发生变更，必须立即进行品质验证和测试。

Tests and inspection shall be performed in accordance with the requirements, tests and methods contained herein. A re-qualification test shall be conducted immediately following all major process changes.

## 2. 参考文件 **Referenced Documents:**

EIA364

MIL-STD-883B: Methods 2022 solder Testing.

ISO 7816-1:Identification Cards-integrated circuit cards with contact-dimension and location of the contacts.

GSM11.11:IETS subscriber identity module-interface specification

EIA 481-3 ,SMD tapping standard

若某些项目被发现本规格书中的内容与以上参考文件要求不一致时，一律依本规格书中的内容为测试依据。

In case of any contradiction between this document and referenced documents, this document will take precedence.

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### 3. 规格要求 Requirements:

#### 3.1 应用条件 Application Condition:

##### 3.1.1 额定电流: 0.5Amps DC Max. per contact

CURRENT RATING : 0.5Amps DC Max. per contact

##### 3.1.2 额定电压: 100 Volt DC Max.

VOLTAGE RATING : 100 Volt DC Max

##### 3.1.3 使用环境 Operating Environment:

温度: -25°C to +85°C,相对湿度:25%~85%,此条件下功能不可失效。

Temperature:-25°C to +85°C, Relative Humidity:25%~85%, Without loss of function.

##### 3.1.4 储存环境 Storage Environment:

温度: -40°C to +85°C,相对湿度:25%~85%或更低,此条件下功能不可失效。

Temperature:-40°C to +85°C, Relative Humidity: 25%~85% or Less, Without loss of function.

#### 3.2 绿色环保要求 Health, Safety and Environment

此产品中所有涉及环保有关的有害物质管控标准请参考嘉华系统文件:[JH-GP-213](#)

Hazardous substances (Environment related to be controlled substances) contained in this product should comply with the regulations specified by FAF's [JH-GP-213](#).

#### 3.3 测试说明 Test Description

此产品性能须满足本文件第 4 节中的各项规格要求。除非有特别申明,所有的测试和量测必须在以下条件中进行:

The product is designed to meet the requirements specified in section 3.4. Unless otherwise specified, all tests and measurements are to be performed under the following conditions:

温度 Temperature: 15 to 35°C

相对湿度 Relative Humidity: 25% to 75%

大气压 Atmospheric Pressure: 650 to 800 millimeters (25.6 to 31.5 inches) of Mercury.

### 4.测试规范和方法 Test Requirements and Methods

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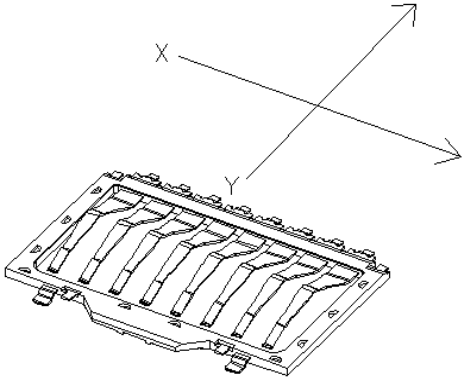
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4.1 外观 Appearance		
项目 Items	规格要求 Requirements	测试方法 Test Methods
4.1 产品外观和尺寸检查  Appearance	所有零件必须组装完好,不能出现毛边,变形,刮伤,以及任何外观破坏等异常;  All components shall be properly assembled and free of burrs, warps, scratches, broken chips, and other abnormalities	依照相应的文件和规格书进行外观,功能,及尺寸的检验量测.  Visual, functional, and dimensional inspection complies with applicable specification and document.
4.2 电气性能 Electrical Performance :		
4.2.1 接触阻抗  Low level contact resistance	初始接触阻抗: 100mΩ Max;  试验后接触阻抗: 150mΩ Max;  Initial: 100mΩ Max;  After test: 150mΩ Max;	测量接触阻抗, 测试电流小于 10mA Measure contact resistance of product and test card PCB with less than current of 10 mA ( exception for the conductor resistance)
4.2.2 绝缘阻抗 Insulation resistance	初始绝缘阻抗: 1000 MΩ Min 试验后绝缘阻抗: 100 MΩ Min  Initial:1000 MΩ Min After test:100 MΩ Min	测试电压: 直流 500V, 测试时间: 1 分钟, 测试相邻两端子之间的绝缘阻抗 Give DC 500V Voltage for 1 minutes and then measure insulation resistance of contact and contact
4.2.3 耐电压 Dielectric withstanding voltage	产品既无电火花也无气体产生 漏电流最大 0.2mA After the test, Neither creeping discharge nor flashover shall occur. Leakage current 0.2 mA Max	两相邻端子之间加载交流 500V 电压 1 分钟; Give AC 500 V in near contact and insulator for 1 minute
4.2.4 温升 Temperature Rise	温度升高不超过 30 °C; Temperature Rise 30 °C Max;	产品插卡后当额定电流通过时,测试端子之温度升高; Mate card and measure the temperature rise of contact,when rated current is passed

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4.3 机械性能 Mechanical Performance :		
4.3.1 正向力 Normal Force	正向力: 30gf~70gf; Normal Force : 30gf~70gf;	<p>产品焊板后, 将弹片端子以 25±3 millimeters/minute 的速度垂直压缩到塑胶面上表面位置, 测量正向力 NF.取值时从回程曲线上取距塑胶面 0.1mm 位置的 NF. 使用量程为 2Kg 的荷重元进行测试;</p> <p>After Soldering of testing product at PCB, vertical compression the clip terminal to distance of 0.1mm of the plastic surface at the speed of 25+3 millimeters/minute and testing the positive force NF at this time;</p>
4.3.2 抓板力 Shear force	抓板力: 3.5kgf Min; Shear force: 3.5kgf Min;	<p>产品焊板后, 测量产品拔出力, 测试速度: 25+3mm/min,测试如图两个方向</p> <p>After Soldering of testing product at PCB, Measure pulling force of Plug at 25±3mm/min;</p> 
4.3.3 耐久 Durability	<ol style="list-style-type: none"> <li>1. 试验后接触阻抗: 150mΩMax;</li> <li>2. 产品无断裂、无破损;</li> <li>3. 端子正向力: 30~70gf;</li> <li>4. 端子弹高: 0.55±0.08mm</li> </ol> <ol style="list-style-type: none"> <li>1. Aftertesting,contact resistance : 150 mΩΩMax;</li> <li>2. No have fracture, crack;</li> <li>3. Normal Force: 30~70gf;</li> <li>4. Height of Spring: 0.55±0.08mm</li> </ol>	<p>产品焊板后, 将弹片端子以 25±3 millimeters/minute 的速度垂直压缩到塑胶面位置,重复 5000 次;</p> <p>After Soldering of testing product at PCB, Repeat vertical compression the clip terminal to the plastic surface at the speed of 25+3 millimeters/minute as 5000cycles</p>

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<p>4.3.4 振动 Vibration</p>	<p>1 没有物理损坏, 端子无变形 2 不产生超过 1 微秒的瞬断 1No have fracture , crack, terminal contact point shake of product 2 No electrical discontinuity longer than 1 u sec.</p>	<p>产品焊板后测试, 测试频率: 10-55Hz 振幅: 1.50mm; Mate card and subjected to the following vibration conditions, for a period of 5 minutes per 1 cycle,10 cycle per 1 axis total 30 cycles per 3 axis.perpendicular axes, with passing DC 1mA during the test. Amplitude: 1.50mm P-P or 19.6m/s<sup>2</sup>{2G} requency : 10-55Hz. Per EIA-364-28</p>
<p>4.3.5 机械冲击 Mechanical Shock</p>	<p>1 没有物理损坏, 端子无变形 2 不产生超过 1 微秒的瞬断 1No have fracture , crack, terminal contact point shake of product 2 No electrical discontinuity longer than 1 u sec.</p>	<p>产品插卡后依如下条件测试: 电流: DC 1mA Mate card and subjected to the following shock conditions. 3 mutually perpendicular axis, passing DC 1mA current during the test. (Total of 18 shocks) Test pulse: Half Sine Peak value: 490m/s<sup>2</sup>{50G} Duration: 11ms, velocity change 3.44m/s Per EIA-364-27</p>

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项目 Items	规格要求 Requirements	测试方法 Test Methods
<b>4.4 环境性能 Environmental Performance :</b>		
4.4.1 恒温恒湿 Humidity	1. 产品无损坏, 端子无变形 2. 测试后接触阻抗: 150mΩMax 1 .No have fracture crack ,terminal contact point deflection and shake of product 2. After testing contact resistance: 150 mΩ Max	配合后的产品在以下条件下测试: 温度: 40±2°C; 相对湿度: 92~98% 时间: 96 hours Mated connectors shall be subjected to the following condition: Temperature: 40±2°C Relative humidity: 92 to 98% Period: 96 hours
4.4.2 耐低温 Low Temperature	1. 产品无损坏,端子无变形; 2. 测试后接触阻抗:150 mΩMax 1. No have fracture crack, terminal Contact point deflection and shake of product 2. After testing contact resistance: 150 mΩ Max	配合后的产品在以下条件下测试: 温度: -40±2°C; 时间: 96 hours The card shall be mated and exposed to the condition of -40±2°C for 96 hours. Recovery time 1~2 hours
4.4.3 耐高温 High temperature	1 产品无损坏, 端子无变形 2. 试验后接触阻抗: 150 mΩMax  1.No have fracture crack ,terminal contact point deflection and shake of product 2.After testing contact resistance: 150 mΩ Max;	配合后的产品在以下条件下测试: 温度: 80±2°C 时间: 96h  Mated connectors shall be subjected to the following condition: temperature: 80±2°C Duration: 96h

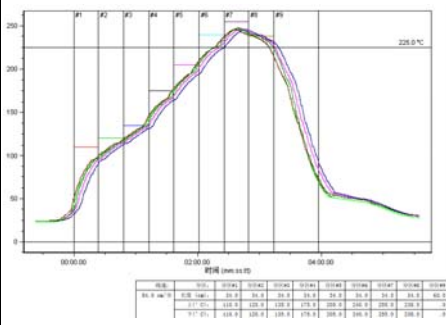
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4.4.4 热冲击 Thermal shock	测试后满足相应机械及电气规格; 测试后接触阻抗: 150 mΩMax  After test: 150 mΩ Max	参考测试标准: EIA-364-32; -30°C和+60°C各 30 分钟, 总计 5 个循环。 Comply with method EIA-364-32. -30°C for 30 minutes and +60°C for 30 minutes for 5 cycles.
4.4.5 盐雾测试 Salt Spray Test	1.产品无损坏, 端子无变形 2. 试验后接触阻抗: 150 mΩMax  1. No have fracture crack ,terminal contact point deflection and shake of product 2. After testing contact resistance: 150 mΩ Max ;	盐水浓度: 5±1% 时间: 48 小时 温度: 35±2°C Mated connector shall be subjected to the following condition Concentration : 5±1% Spray time : 48hours Temperature : 35±2°C
4.4.6 吃锡性测试 Solder ability	焊脚吃锡面积 95%以上  More than 95% of area dipped in molten solder should be coated by solder	温度: 250°C±5°C 粘锡时间: 3±0.5 秒 Solder Temperature : 250°C±5°C Immersion Duration : 3±0.5 seconds
4.4.7 耐 Reflow 高温 Resistance to Reflow Soldering Heat	1.无损坏, 端子无变形; 2.产品结构无破坏;  1.No have fracture crack ,terminal contact point deflection and shake of product 2.No have break down outer feature/structure	根据下图温度条件测试产品的耐焊接热 The connector shall be tested resistance to soldering heat in the following conditions, The temperature shall be measured on the surface of PCB  

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## 4.5 Test Sequence

Group Number	A	B	C	D	E	F	G	H	J
Contact Resistance	1,6		1,3,5	1,5,7	1,3,5	1,3			
Insulation Resistance				2,8					
Dielectric Withstanding Voltage				3,9					
Temperature Rise									1
Normal force	2,4								
Shear force		1							
Durability	3								
Vibration			2						
Mechanical Shock			4						
High Relative Humidity Exposure				6					
Low Temperature Exposure					2				
High Temperature Exposure					4				
Thermal Shock				4					
Salt Spray Test						2			
Solderability							1		
Resistance to Soldering reflow Heat								1	
Height of Spring	5								

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